

ANTREX Electronics

Electronic Components Sourcing Information

Product Reference Information

Part Number: BAP65-05W,115
Manufacturer: NXP USA Inc.
Package: SC-70, SOT-323
Availability: Please confirm with sales

Product Page:

<https://antrexco.com/product/details/nxp-usa-inc/bap65-05w-115.html>

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Note:

This PDF includes an ANTREX product reference cover page.

The original manufacturer datasheet follows from the next page.



BAP65-05W

Silicon PIN diode

Rev. 3.1 — 28 January 2019

Product data sheet

1 Product profile

1.1 General description

Two planar PIN diodes in an SOT323 small SMD plastic package.

1.2 Features and benefits

- Two elements in common cathode configuration
- High voltage, current controlled
- RF resistor for RF switches
- Low diode capacitance
- Low diode forward resistance
- AEC-Q101 qualified

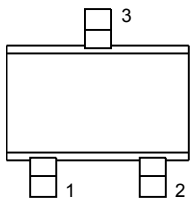
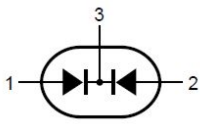
1.3 Applications

- RF attenuators and switches
- Bandswitch for TV tuners
- Series diode for mobile communication transmit/receive switch



2 Pinning information

Table 1. Discrete pinning

Pin	Description	Simplified outline	Graphic symbol
1	anode (a ₁)	 sot323_so Top view	
2	anode (a ₂)		
3	common cathode		

3 Ordering information

Table 2. Ordering information

Type number	Package		
	Name	Description	Version
BAP65-05W	-	plastic surface-mounted package; 3 leads	SOT323

4 Marking

Table 3. Marking

Type number	Marking code
BAP65-05W	V6%

5 Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V _R	continuous reverse voltage		-	30	V
I _F	continuous forward current		-	100	mA
P _{tot}	total power dissipation	T _{sp} ≤ 90 °C	-	240	mW
T _{stg}	storage temperature		-65	+150	°C
T _j	junction temperature		-65	+150	°C
T _{amb}	ambient temperature		-40	+85	°C

6 Thermal characteristics

Table 5. Thermal characteristics

Symbol	Parameter	Conditions	Typ	Unit
$R_{th(j-sp)}$	thermal resistance from junction to solder point		250	K/W

7 Characteristics

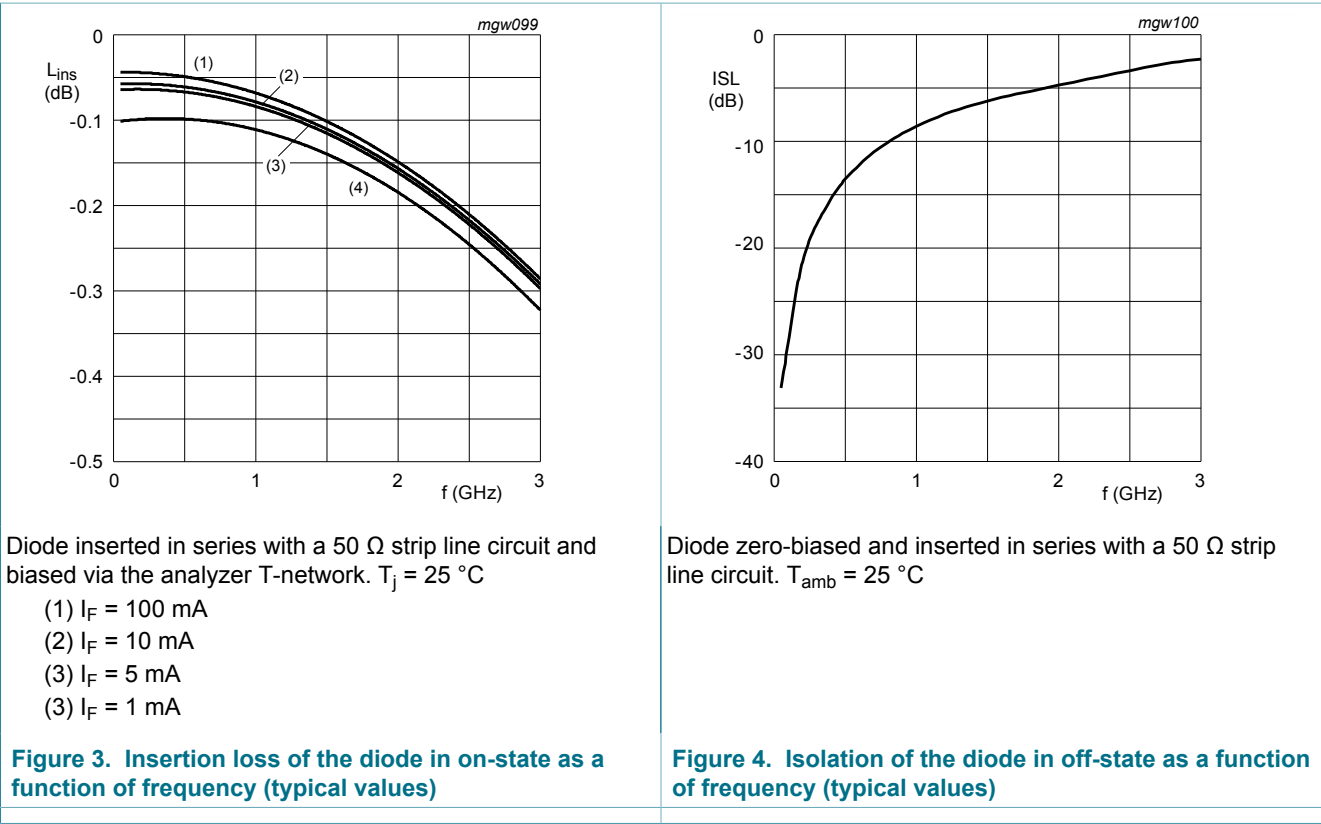
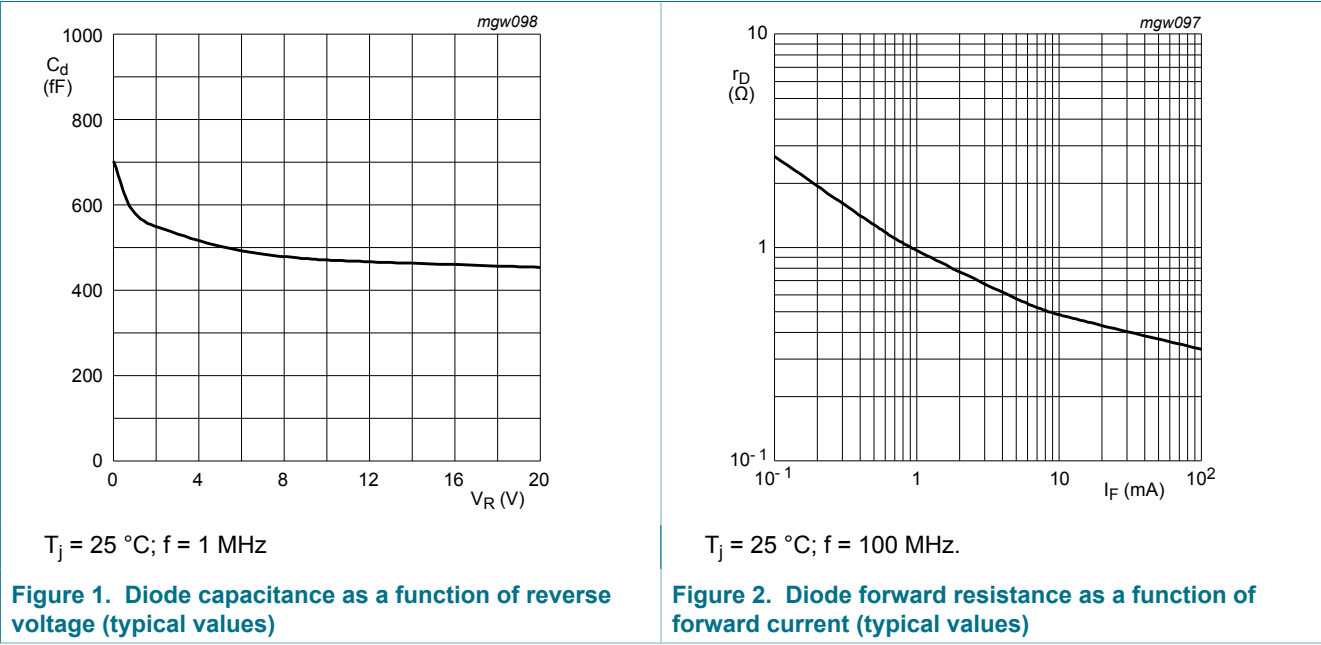
Table 6. Characteristics
 $T_j = 25\text{ }^{\circ}\text{C}$ unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_F	forward voltage	$I_F = 50\text{ mA}$	-	0.9	1.1	V
I_R	reverse leakage current	$V_R = 20\text{ V}$	-	-	20	nA
C_d	diode capacitance	$f = 1\text{ MHz}$ (see Figure 1)				
		$V_R = 0\text{ V}$	-	0.7	-	pF
		$V_R = 1\text{ V}$	-	0.575	0.9	pF
		$V_R = 3\text{ V}$	-	0.525	0.8	pF
		$V_R = 20\text{ V}$	-	0.425	-	pF
r_D	diode forward resistance	$f = 100\text{ MHz}$ (see Figure 2)				
		$I_F = 1\text{ mA}$	-	1	-	Ω
		$I_F = 5\text{ mA}$ [1]	-	0.65	0.95	Ω
		$I_F = 10\text{ mA}$ [1]	-	0.56	0.9	Ω
		$I_F = 100\text{ mA}$	-	0.35	-	Ω
ISL	isolation	$V_R = 0\text{ V}$ (see Figure 4)				
		$f = 900\text{ MHz}$	-	9.3	-	dB
		$f = 1800\text{ MHz}$	-	5.3	-	dB
		$f = 2450\text{ MHz}$	-	3.5	-	dB
L_{ins}	insertion loss	See Figure 3 .				
		$I_F = 1\text{ mA}$				
		$f = 900\text{ MHz}$	-	0.11	-	dB
		$f = 1800\text{ MHz}$	-	0.17	-	dB
		$f = 2450\text{ MHz}$	-	0.24	-	dB
		$I_F = 5\text{ mA}$				
		$f = 900\text{ MHz}$	-	0.08	-	dB
		$f = 1800\text{ MHz}$	-	0.14	-	dB
		$f = 2450\text{ MHz}$	-	0.21	-	dB
		$I_F = 10\text{ mA}$				
		$f = 900\text{ MHz}$	-	0.08	-	dB
		$f = 1800\text{ MHz}$	-	0.14	-	dB
		$f = 2450\text{ MHz}$	-	0.21	-	dB
L_{ins}	insertion loss	$I_F = 100\text{ mA}$				
		$f = 900\text{ MHz}$	-	0.06	-	dB
		$f = 1800\text{ MHz}$	-	0.13	-	dB
		$f = 2450\text{ MHz}$	-	0.2	-	dB

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
τ_L	charge carrier life time	when switched from $I_F = 10$ mA to $I_R = 6$ mA; $R_L = 100\ \Omega$; measured at $I_R = 3$ mA	-	0.17	-	μs
L_S	series inductance	$I_F = 100$ mA; $f = 100$ MHz	-	1.4	-	nH

[1] Guaranteed on AQL basis; inspection level S4, AQL 1.0

8 Graphical data



9 Package outline

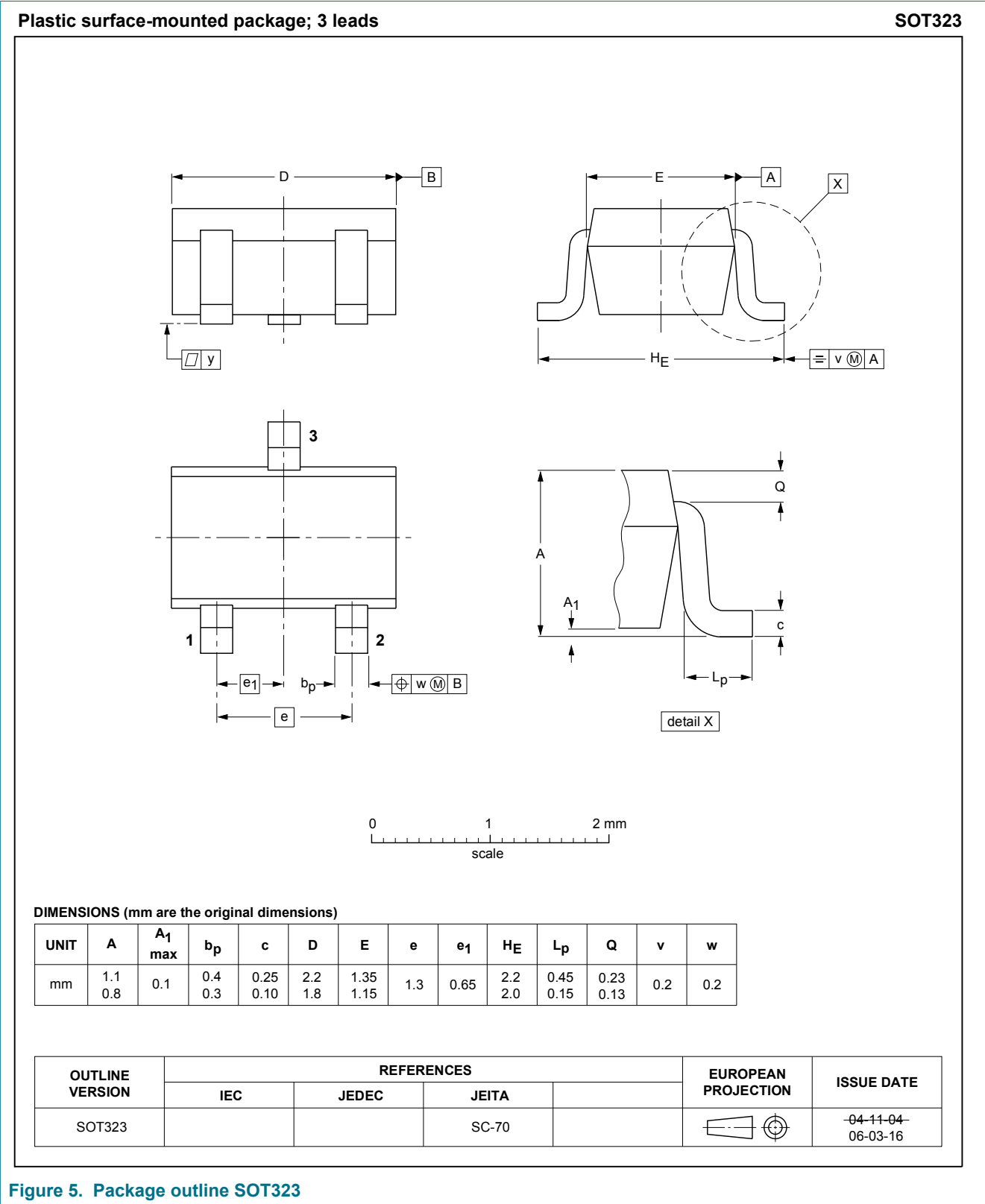


Figure 5. Package outline SOT323

10 Revision history

Table 7. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
BAP65-05W v.3.1	20190128	Product data sheet	-	BAP65-05W v.3
Modifications:	• Changed title to Silicon PIN diode			
BAP65-05W v.3	20181211	Product data sheet	-	BAP65-05W v.2
Modifications:	• Section 1.2 "Features and benefits" has been updated. • The "Legal information" pages have been updated.			
BAP65-05W v.2	20100927	Product data sheet	-	BAP65-05W v.1

11 Legal information

11.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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Please be aware that important notices concerning this document and the product(s) described herein, have been included in section 'Legal information'.